

SOT991-1

plastic very thin fine-pitch ball grid array package; 56 balls;
body 4 x 4.5 x 0.65 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	VFBGA56
Package type industry code	VFBGA56
Package style descriptive code	VFBGA (very thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	7-2-2007

Table 1. Package summary

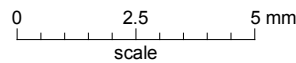
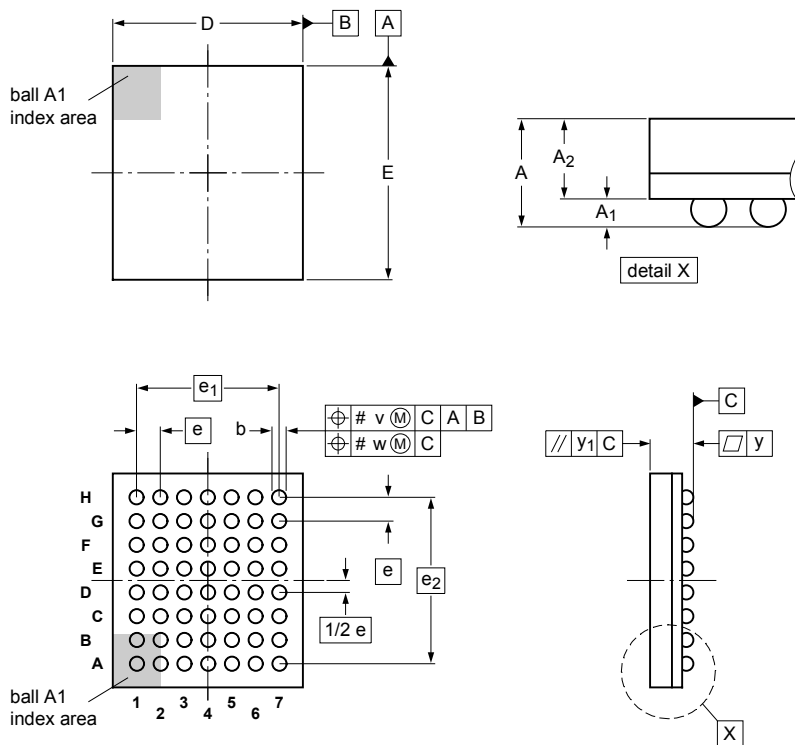
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.9	-	4	4.1	mm
E	package width	4.4	-	4.5	4.6	mm
A	seated height	[tbd]	-	1	1	mm
A ₂	package height	0.6	-	0.65	0.75	mm
n ₂	actual quantity of termination	-	-	56	-	



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2. Package outline

VFBGA56: plastic very thin fine-pitch ball grid array package; 56 balls; body 4 x 4.5 x 0.65 mm SOT991-1



DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
mm	1	0.25 0.15	0.75 0.60	0.35 0.25	4.1 3.9	4.6 4.4	0.5	3	3.5	0.15	0.05	0.08	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT991-1	---	---	---			07-02-06 07-02-07

Fig. 1. Package outline VFBGA56 (SOT991-1)

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3. Legal information

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For sales office addresses, please send an email to: salesaddresses@nxp.com
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